## **UNR3113**

## Silicon PNP epitaxial planer type

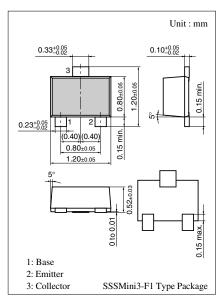
### For digital circuit

#### ■ Features

- Costs can be reduced through downsizing of the equipment and reduction of the number of parts.
- Mounting ratio: 99.9% to 100%
- 10 000 pcs per 1 reel, reducing reel change frequency.

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector to base voltage	$V_{CBO}$	-50	V
Collector to emitter voltage	V <sub>CEO</sub>	-50	V
Collector current	$I_{C}$	-100	mA
Total power dissipation	P <sub>T</sub>	100	mW
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C



Marking Symbol: 6C

#### Internal Connection

$$\begin{array}{c}
R_1 \\
(47 \text{ k}\Omega) \\
B \circ \longrightarrow W \\
R_2 \\
(47 \text{ k}\Omega) & E
\end{array}$$

## ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = -50 \text{ V}, I_E = 0$			- 0.1	μΑ
	I <sub>CEO</sub>	$V_{CE} = -50 \text{ V}, I_B = 0$			- 0.5	μΑ
Emitter cutoff current	I <sub>EBO</sub>	$V_{EB} = -6 \text{ V}, I_C = 0$			- 0.1	mA
Collector to base voltage	$V_{CBO}$	$I_C = -10 \ \mu A, I_E = 0$	-50			V
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	80			
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -10 \text{ mA}, I_B = -0.3 \text{ mA}$			- 0.25	V
High-level output voltage	V <sub>OH</sub>	$V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	-4.9			V
Low-level output voltage	V <sub>OL</sub>	$V_{CC} = -5 \text{ V}, V_B = -3.5 \text{ V}, R_L = 1 \text{ k}\Omega$			- 0.2	V
Input resistance	R <sub>1</sub>		-30%	47	+30%	kΩ
Resistance ratio	R <sub>1</sub> /R <sub>2</sub>		0.8	1.0	1.2	
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

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